

# STARPOWER

SEMICONDUCTOR

**IGBT**

## GD225HFL170C6S

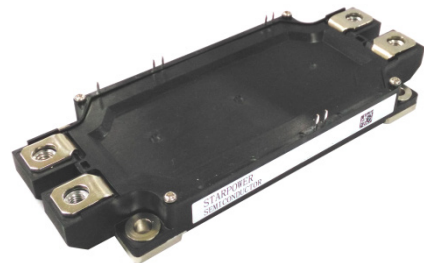
**1700V/225A 2 in one-package**

### General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

### Features

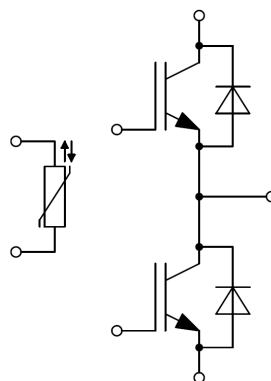
- Low  $V_{CE(sat)}$  SPT+ IGBT technology
- 10 $\mu$ s short circuit capability
- $V_{CE(sat)}$  with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



### Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

### Equivalent Circuit Schematic



**Absolute Maximum Ratings**  $T_C=25^{\circ}\text{C}$  unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
$V_{CES}$	Collector-Emitter Voltage	1700	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C=25^{\circ}\text{C}$	385	A
	@ $T_C=100^{\circ}\text{C}$	225	A
$I_{CM}$	Pulsed Collector Current $t_p=1\text{ms}$	450	A
$P_D$	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	1648	W

**Diode**

Symbol	Description	Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage	1700	V
$I_F$	Diode Continuous Forward Current	225	A
$I_{FM}$	Diode Maximum Forward Current $t_p=1\text{ms}$	450	A

**Module**

Symbol	Description	Value	Unit
$T_{jmax}$	Maximum Junction Temperature	175	$^{\circ}\text{C}$
$T_{jop}$	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
$V_{ISO}$	Isolation Voltage RMS, $f=50\text{Hz}$ , $t=1\text{min}$	4000	V

**IGBT Characteristics**  $T_c=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=225\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		2.00	2.45	V	
		$I_C=225\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		2.40			
		$I_C=225\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		2.50			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=9.0\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.4	6.2	7.4	V	
$I_{CES}$	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			1.0	mA	
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			400	nA	
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		15.3		nF	
$C_{res}$	Reverse Transfer Capacitance				0.54		nF
$Q_G$	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		1.83		$\mu\text{C}$	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=900\text{V}, I_C=225\text{A}, R_G=6.2\Omega, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		230		ns	
$t_r$	Rise Time			100		ns	
$t_{d(off)}$	Turn-Off Delay Time			500		ns	
$t_f$	Fall Time			400		ns	
$E_{on}$	Turn-On Switching Loss				60.0		mJ
$E_{off}$	Turn-Off Switching Loss				48.0		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=900\text{V}, I_C=225\text{A}, R_G=6.2\Omega, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		250		ns	
$t_r$	Rise Time			110		ns	
$t_{d(off)}$	Turn-Off Delay Time			650		ns	
$t_f$	Fall Time			530		ns	
$E_{on}$	Turn-On Switching Loss				92.5		mJ
$E_{off}$	Turn-Off Switching Loss				72.0		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=900\text{V}, I_C=225\text{A}, R_G=6.2\Omega, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$		255		ns	
$t_r$	Rise Time			115		ns	
$t_{d(off)}$	Turn-Off Delay Time			680		ns	
$t_f$	Fall Time			570		ns	
$E_{on}$	Turn-On Switching Loss				100		mJ
$E_{off}$	Turn-Off Switching Loss				80.0		mJ
$I_{SC}$	SC Data	$t_p \leq 10\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=1000\text{V}, V_{CEM} \leq 1700\text{V}$		900		A	

**Diode Characteristics**  $T_c=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_F$	Diode Forward Voltage	$I_F=225\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		1.80	2.25	V
		$I_F=225\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		1.95		
		$I_F=225\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		1.90		
$Q_r$	Recovered Charge			60.0		$\mu\text{C}$
$I_{RM}$	Peak Reverse Recovery Current	$V_R=900\text{V}, I_F=225\text{A},$ $-di/dt=3200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^\circ\text{C}$		220		A
$E_{rec}$	Reverse Recovery Energy			32.0		mJ
$Q_r$	Recovered Charge			100		$\mu\text{C}$
$I_{RM}$	Peak Reverse Recovery Current	$V_R=900\text{V}, I_F=225\text{A},$ $-di/dt=3200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^\circ\text{C}$		240		A
$E_{rec}$	Reverse Recovery Energy			58.0		mJ
$Q_r$	Recovered Charge			115		$\mu\text{C}$
$I_{RM}$	Peak Reverse Recovery Current	$V_R=900\text{V}, I_F=225\text{A},$ $-di/dt=3200\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^\circ\text{C}$		250		A
$E_{rec}$	Reverse Recovery Energy			66.0		mJ

**NTC Characteristics**  $T_c=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{25}$	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of $R_{100}$	$T_c=100^\circ\text{C}, R_{100}=493.3\Omega$	-5		5	%
$P_{25}$	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

**Module Characteristics**  $T_c=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
$L_{CE}$	Stray Inductance		20		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		1.10		$\text{m}\Omega$
$R_{\theta JC}$	Junction-to-Case (per IGBT)			0.091	K/W
	Junction-to-Case (per Diode)			0.145	
$R_{\theta CS}$	Case-to-Sink (per IGBT)		0.029		K/W
	Case-to-Sink (per Diode)		0.047		
$R_{\theta CS}$	Case-to-Sink		0.009		K/W
M	Terminal Connection Torque, Screw M5	3.0		6.0	N.m
	Mounting Torque, Screw M6	3.0		6.0	
G	Weight of Module		350		g

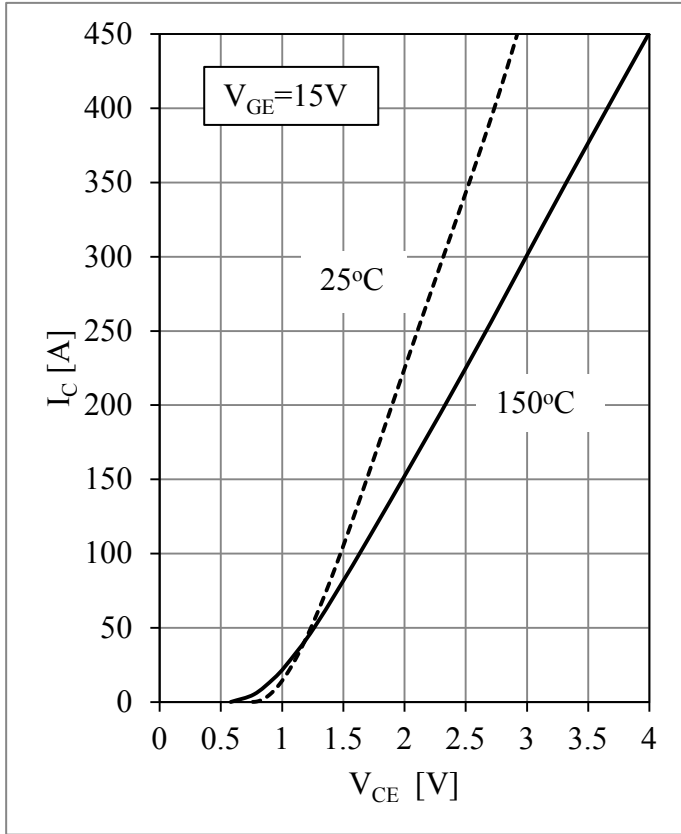


Fig 1. IGBT Output Characteristics

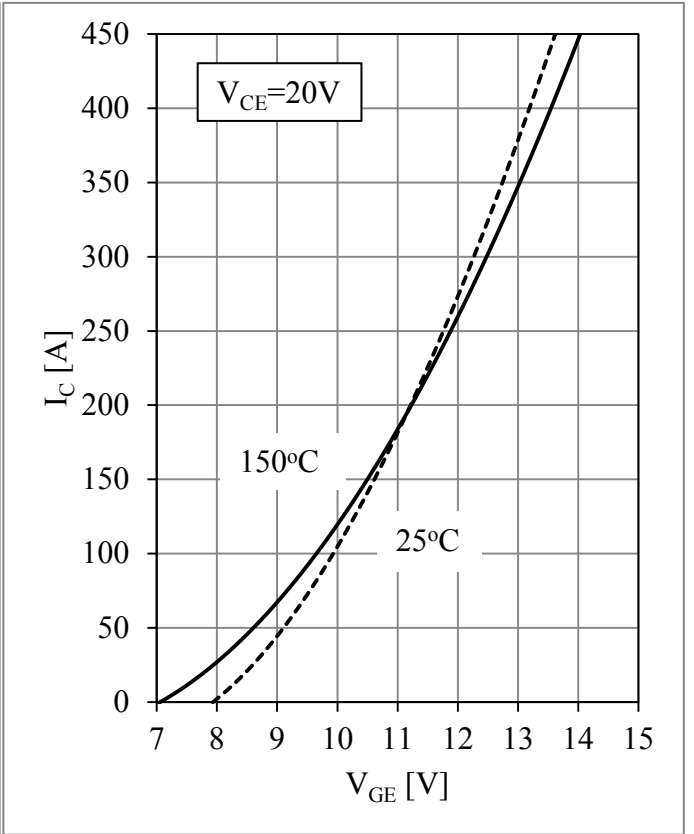


Fig 2. IGBT Transfer Characteristics

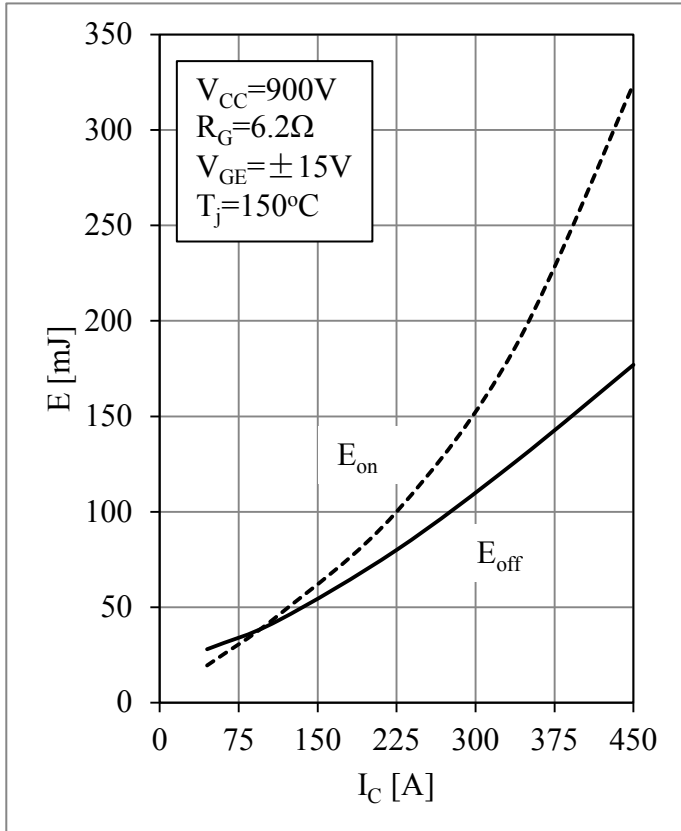


Fig 3. IGBT Switching Loss vs.  $I_C$

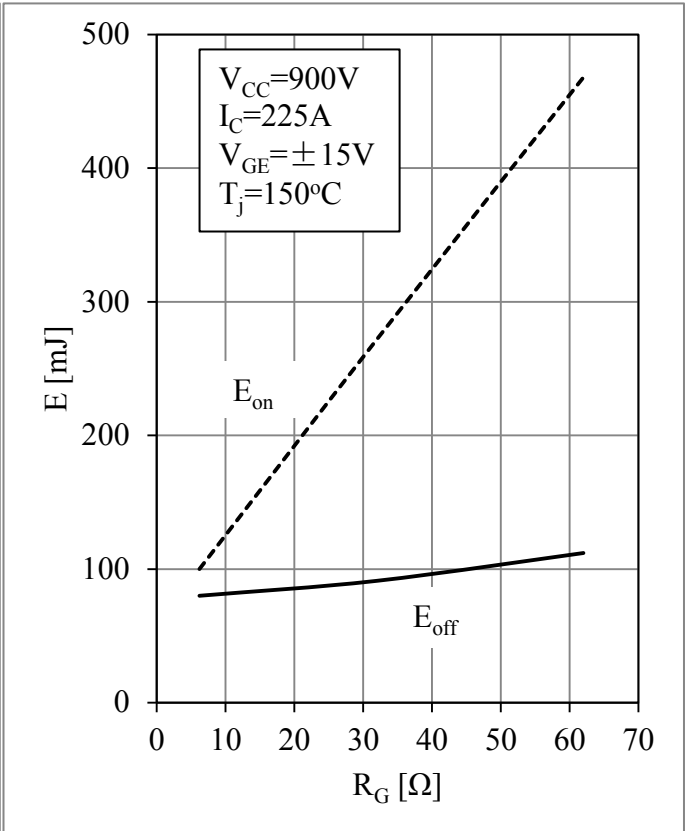


Fig 4. IGBT Switching Loss vs.  $R_G$

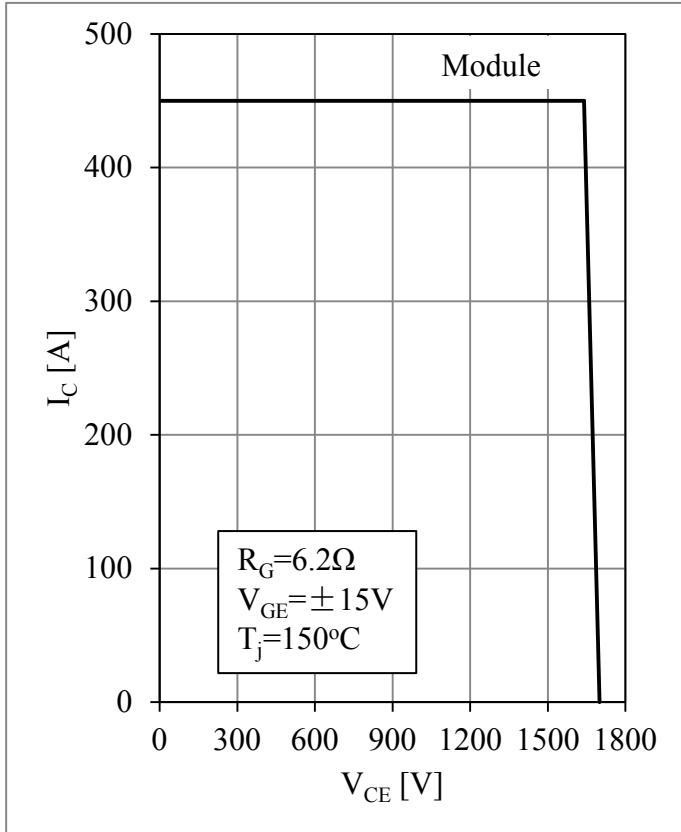


Fig 5. RBSOA

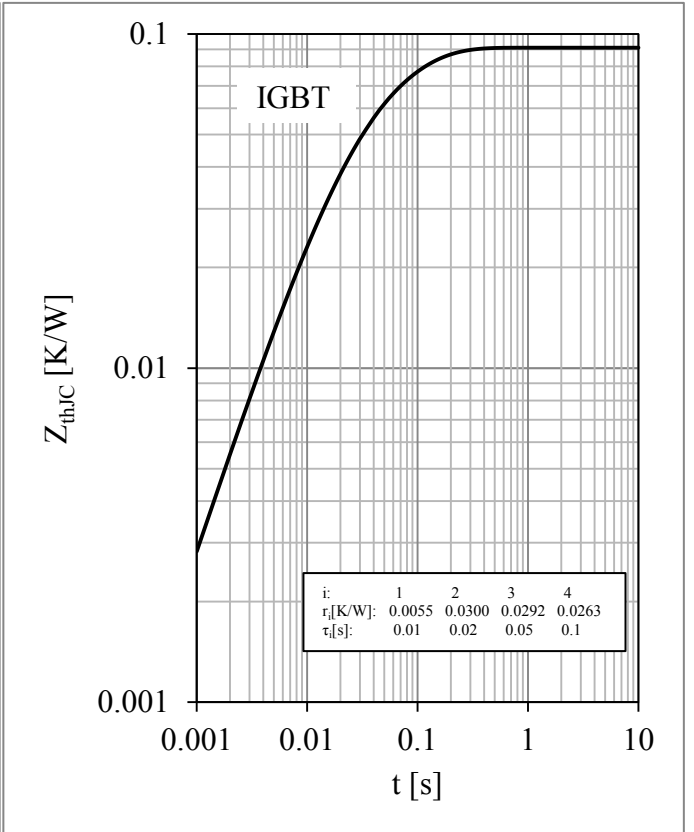


Fig 6. IGBT Transient Thermal Impedance

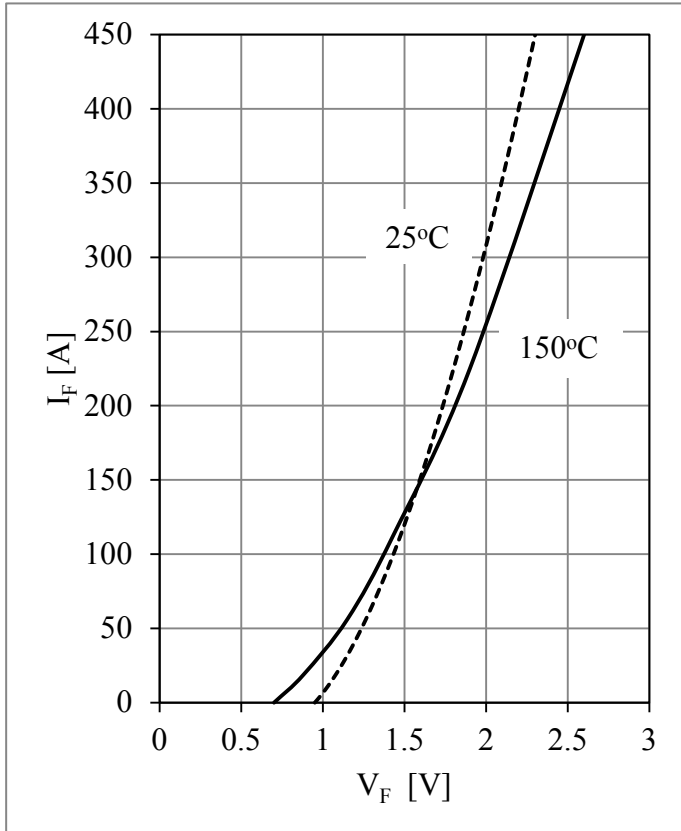


Fig 7. Diode Forward Characteristics

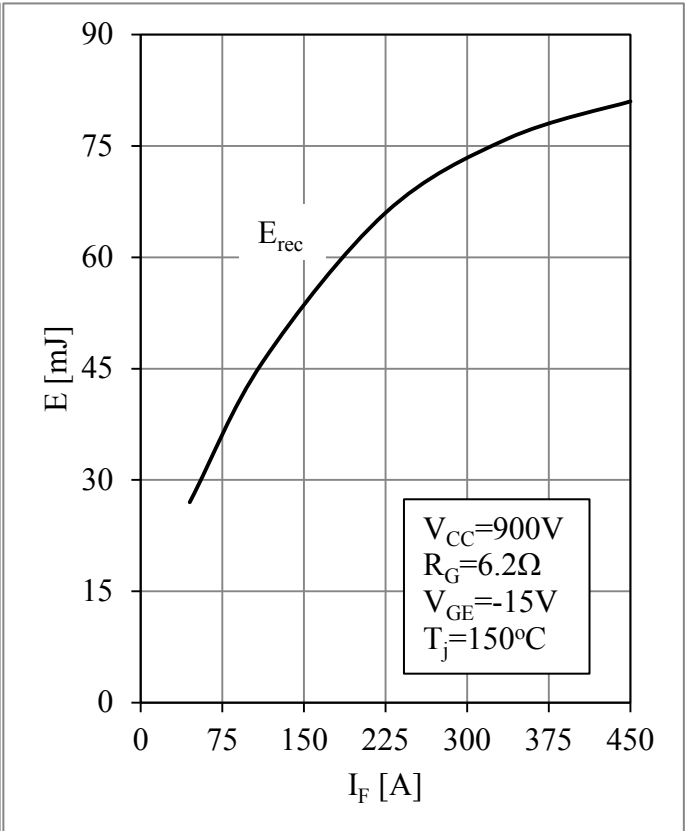


Fig 8. Diode Switching Loss vs.  $I_F$

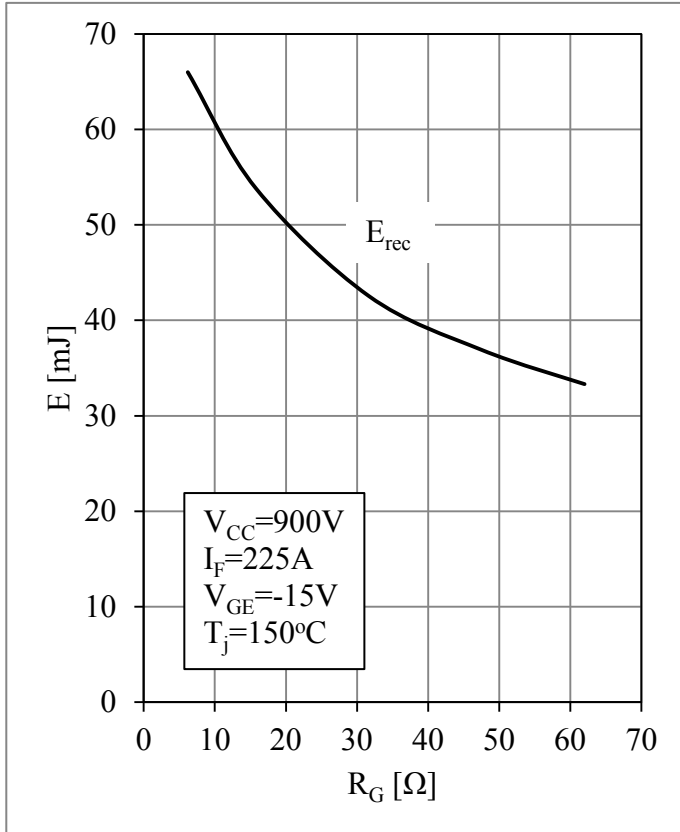


Fig 9. Diode Switching Loss vs.  $R_G$

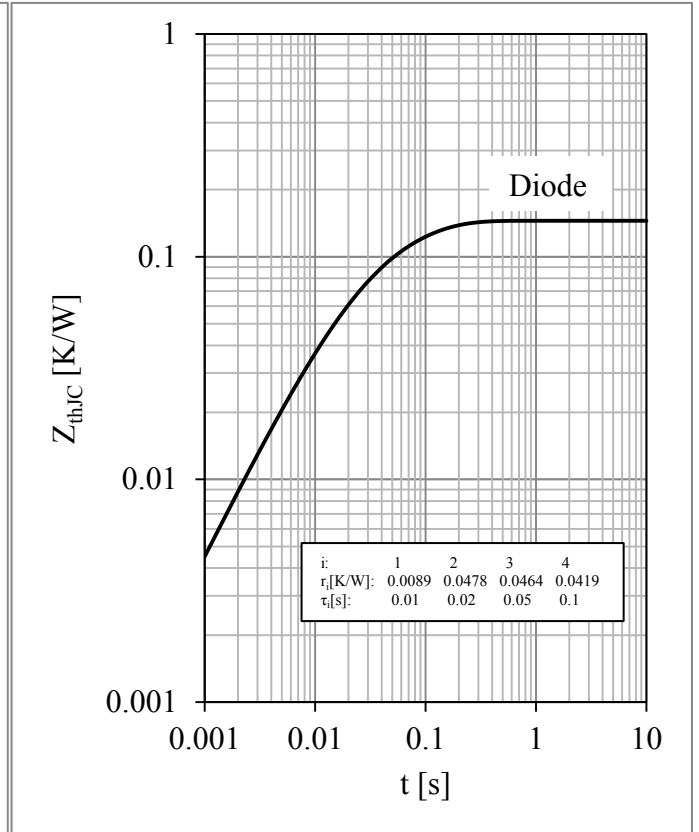


Fig 10. Diode Transient Thermal Impedance

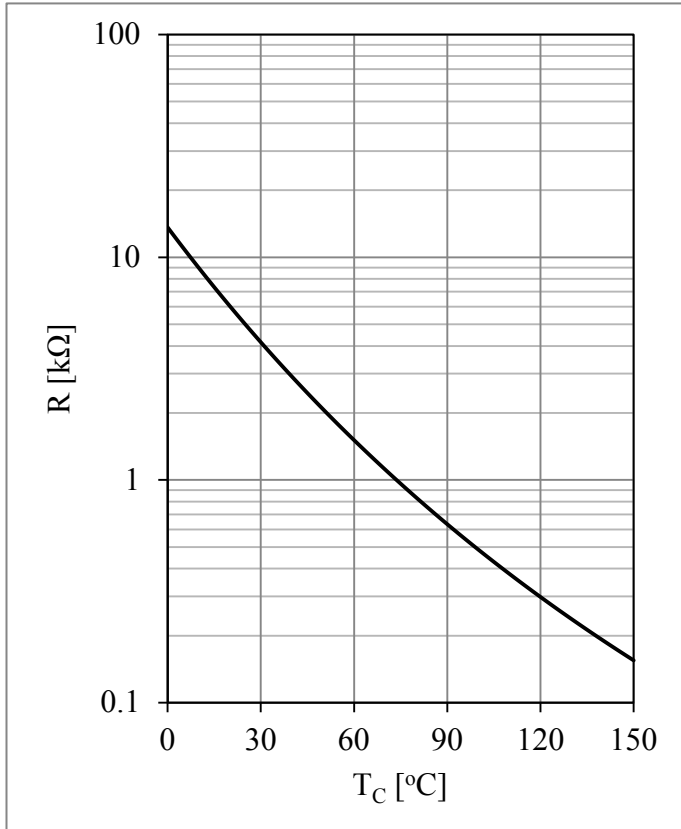
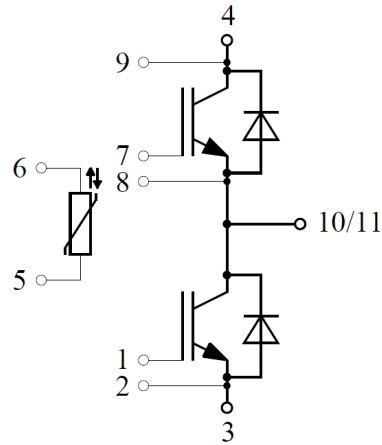


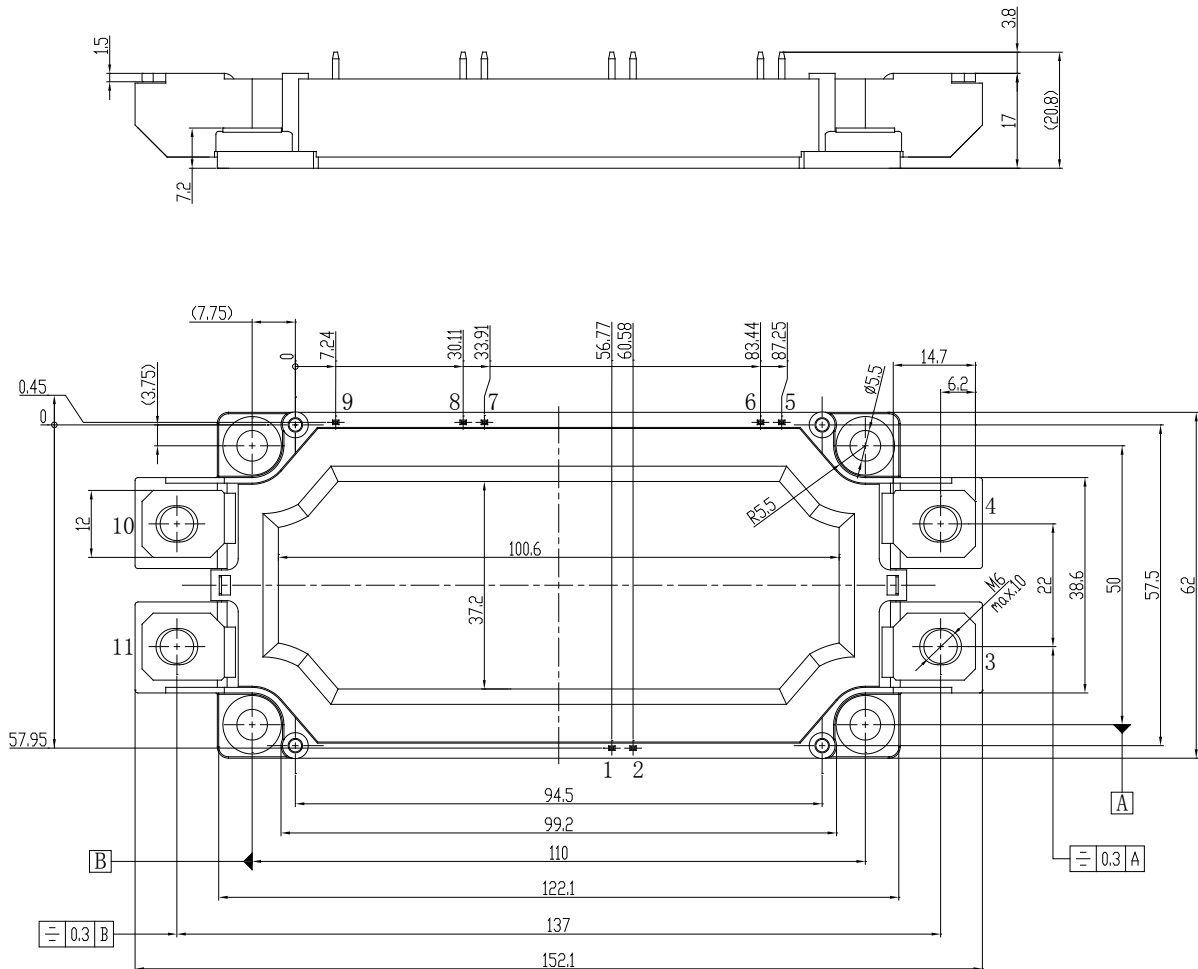
Fig 11. NTC Temperature Characteristic

**Circuit Schematic**



**Package Dimensions**

Dimensions in Millimeters





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